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ABSTRACT OF THE DISCLOSURE

5 The present invention provides a thermal head capable of reliably preventing occurrence of connection failure or insulation failure in each of the layers in a multilayered wiring structure, enabling easy manufacture even in the real edging constitution, capable of maintaining reliability and, further, with no trouble in the terminal connection of a common electrode even if three or more thermal head. There is provided a thermal head comprising a thermal radiating substrate, a temperature keeping layer formed on the thermal radiating substrate, a conductive layer formed on the thermal radiating substrate and an upper surface of the temperature keeping layer comprised of a fused material of nitride and metal or a fused material of oxide and metal, a first interlayer insulation layer formed by oxidization of the conductive layer except a portion of the conductive layer corresponding to a common electrode and a portion of the common electrode corresponding to an external connecting common electrode terminal, a second interlayer insulation layer comprised of insulating ceramics formed on the upper surface of the first interlayer insulation layer, a heat generating resistor member formed above the second interlayer insulation layer and the conductive layer, a common electrode and individual electrodes formed at a part of the upper surface of the heat generating resistor member, and a protecting layer covering the heat generating resistor member, common electrode, individual electrodes and second interlayer insulation layer.